

### PRODUCT DESCRIPTION

Laird Tputty™ 508 is a single part dispensable material designed with automation and vertical stability in mind. Laird has leveraged its knowledge of thermally conductive fillers and resin systems to develop a single part dispensable that demonstrates reliability in a variety of application orientations.

Tputty™ 508 is ideal for applications that can benefit from automation, and allows minimization of SKUs in applications with gap variability. In addition to providing application flexibility and variable gap adaptation, Tputty™ 508 will exert minimum stress on your component while maintaining interface contact to maximize thermal transfer. Combined with Laird's global technical support and global footprint, deploying Tputty™ 508 is easier than ever.

### FEATURES AND BENEFITS

- RoHS Compliant
- Complete Dispensing Solution Options Available
- 3.7 W/mK
- Demonstrated thermal cycling stability
- Low outgassing per ASTM E595
- Available in cartridges (75cc, 180cc, 360cc, 600cc) and pails (1 gallon and 5 gallon)

| Packaging Size | Fill Volume | Fill Weight |
|----------------|-------------|-------------|
| 75cc (2.5 oz)  | 56cc        | 177g        |
| 180cc (6 oz)   | 159cc       | 503g        |
| 360cc (12 oz)  | 326cc       | 1030g       |
| 600cc (20 oz)  | 601cc       | 1900g       |
| 1 gallon       | 4110cc      | 13kg        |
| 5 gallon       | 6320cc      | 20kg        |

### SPECIFICATIONS

| PROPERTY                                           | TYPICAL VALUE                       | METHOD                        |
|----------------------------------------------------|-------------------------------------|-------------------------------|
| Construction                                       | Ceramic filled silicone dispensable | N/A                           |
| Color                                              | Green                               | Visual                        |
| Thermal Conductivity (w/mK)                        | 3.7                                 | Hot Disk                      |
| Flow Rate (75cc taper tip, 0.125" orifice, 40 psi) | 50 g/min                            | Laird Test Method – A16724-00 |
| Density (g/cc)                                     | 3.2                                 | Helium Pycnometer             |
| Flammability                                       | V-0                                 | UL 94                         |
| Temperature Range                                  | -40 to 150°C                        | Laird Test Method             |
| Outgassing TML (weight %)                          | 0.04                                | ASTM E595                     |
| Outgassing CVM (weight %)                          | 0.01                                | ASTM E595                     |
| Dielectric Breakdown                               | >3000 VAC                           | ASTM D149                     |
| Dielectric Constant @ 1MHz                         | 8.62                                | ASTM D150                     |
| Minimum Bond line Thickness                        | 0.09 mm (0.0036")                   | Laird Test Method -A16112-00  |
| Volume Resistivity (ohm-cm)                        | 10 <sup>13</sup>                    | ASTM D257                     |

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A17223-00 Tputty 508 DS\_053017

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